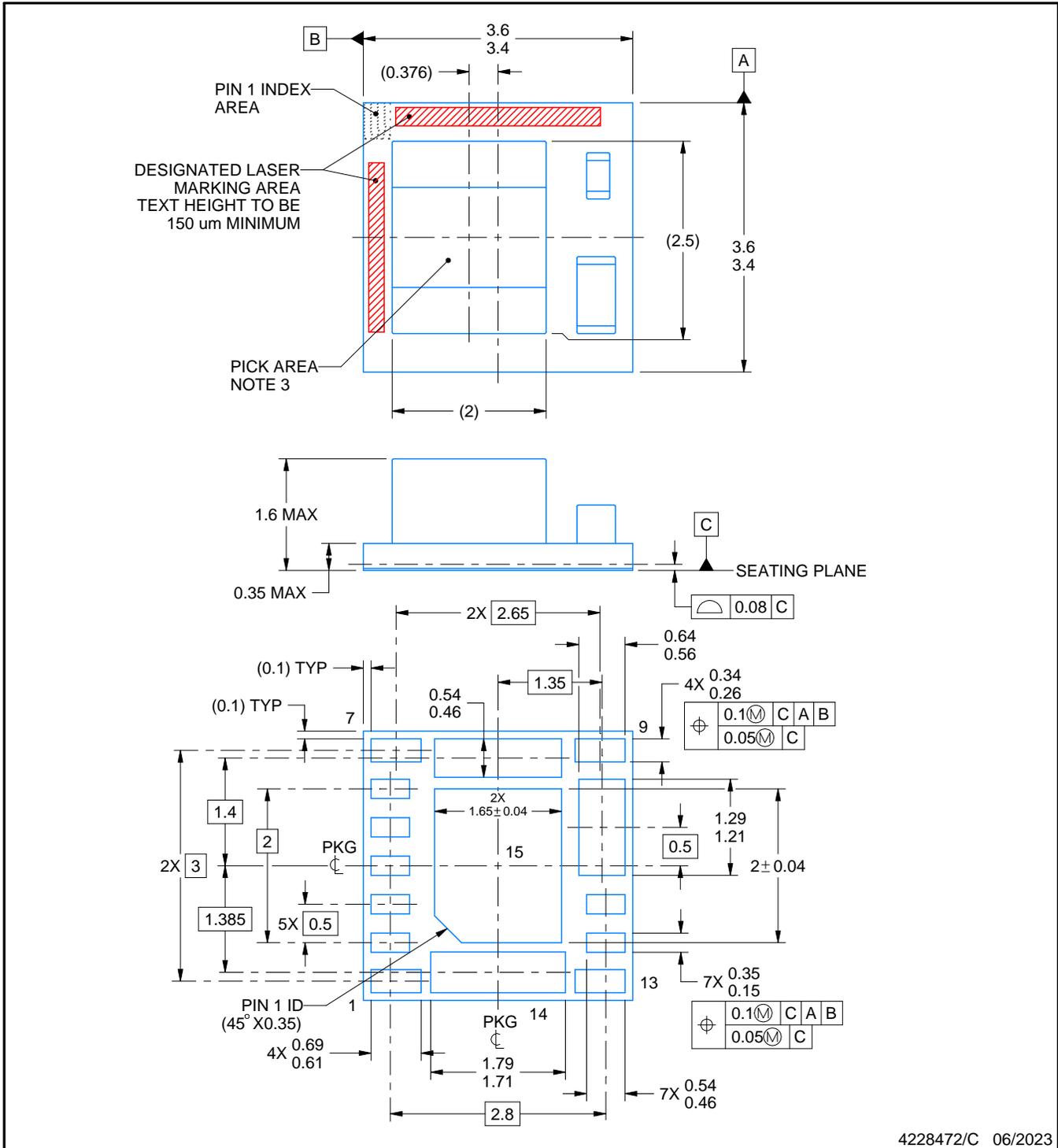


# PACKAGE OUTLINE

## SIT0015A

### MicroSiP™ - 1.6 mm max height

MICRO SYSTEM IN PACKAGE



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MicroSiP is a trademark of Texas Instruments.

#### NOTES:

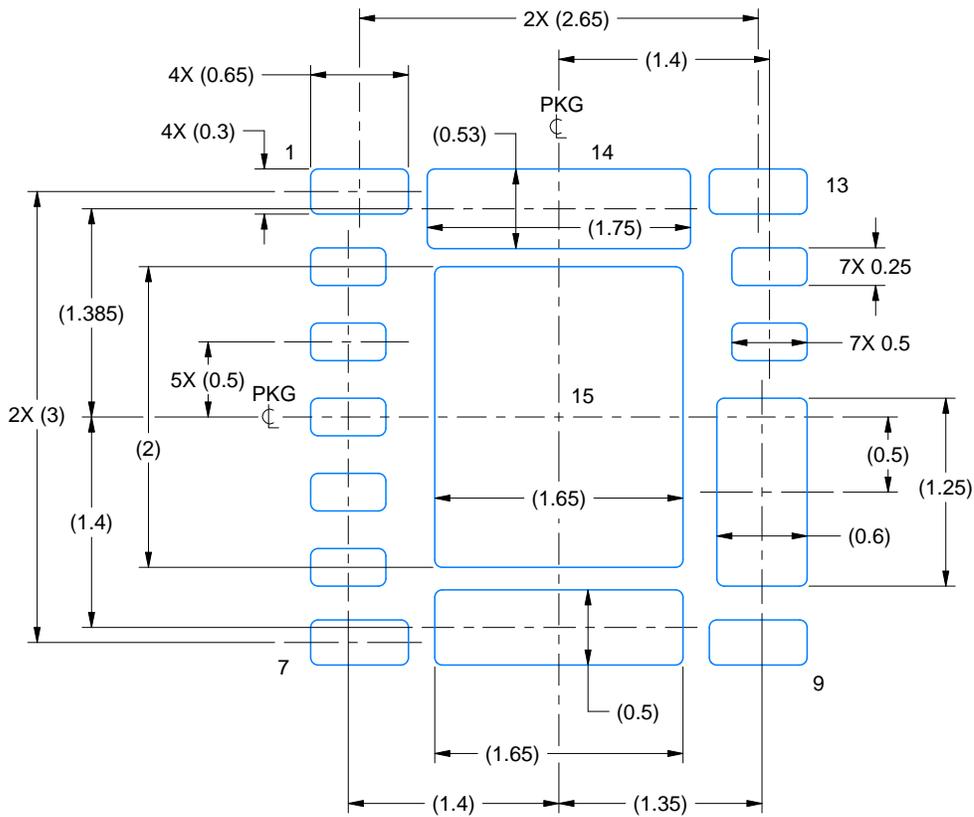
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Pick and place nozzle  $\phi$  1.3 mm or smaller recommended.
4. The package thermal pad must be soldered to the printed circuit board for optimal thermal and mechanical performance.

# EXAMPLE BOARD LAYOUT

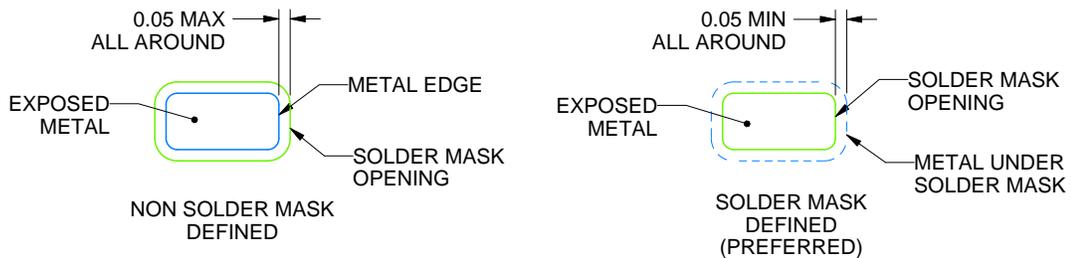
SIT0015A

MicroSiP™ - 1.6 mm max height

MICRO SYSTEM IN PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 20X



SOLDER MASK DETAILS  
NOT TO SCALE

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NOTES: (continued)

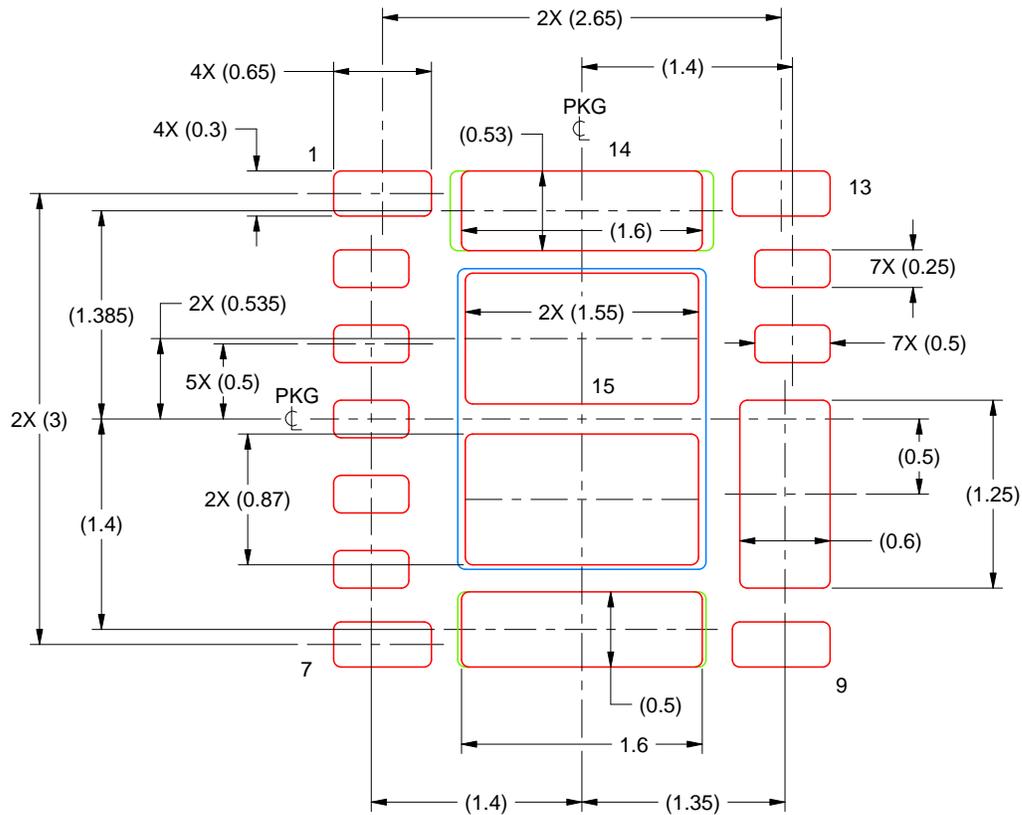
4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/slua271](http://www.ti.com/lit/slua271)).

# EXAMPLE STENCIL DESIGN

SIT0015A

MicroSiP™ - 1.6 mm max height

MICRO SYSTEM IN PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:20X

PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE

PAD 8: 97%  
PAD 14: 91%  
PAD 15: 82%

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NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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